		Carrier and the contract of th	T. D.D.	mile of own
L Num		Search Text ((laminating) with (thermoset\$2 or epoxy)	DB USPAT;	Time stamp 2003/03/14 15:31
. –	, 114	(with (resin)) and packaging	US-PGPUB	!
1 _	82	(((laminating) with (thermoset\$2 or epoxy)	USPAT;	2003/03/14 15:30
(	1	with (resin)) and packaging) and (cure or	US-PGPUB	  -
1	106	<pre>  curing or cured)   ((laminating) with (thermoset\$4 or epoxy)</pre>	USPAT;	   2003/03/14 15:55
; <del>-</del>	1 106	with (resin)) and packaging and (cure or	US-PGPUB	1 2003/03/14 13:00
		curing or cured)		
_	1858	((=::	USPAT;	2003/03/14 15:57
1	•		; US-PGPUB	•
1	: 007	<pre>packaging and (cure or curing or cured) ((sheet or solid) with (thermoset\$4 or</pre>	USPAT;	2003/03/14 16:03
_	1	epoxy) with (resin)) and packaging and	US-PGPUB	2003/03/11 10:03
i	•	(cure or curing or cured)		
-	185		USPAT;	2003/03/14 16:00
		packaging and (cure or curing or cured) and (IC or "integrated circuit" or	US-PGPUB	
		semiconductor)		
i _	366	((sheet) with (thermoset\$4 or epoxy) with	USPAT;	2003/03/14 16:05
		(resin)) and packaging and (cure or curing	US-PGPUB	
İ		or cured)		2002/02/14 16:04
	1	'("5,879,568").PN.	USPAT; US-PGPUB	2003/03/14 16:04
i _	191	((sheet with (thermoset\$4 or epoxy) with	USPAT;	2003/03/14 17:10
	1	resin)) and (cure or curing or cured) and	US-PGPUB	
		(heat or heating) and (packaging) and (IC		
1	1	or "integrated circuit" or semiconductor)		2002/02/14 16-10
1 -	171	! "hot melt" with (definition or define)	USPAT; US-PGPUB	2003/03/14 16:19
-	80	("hot melt" with (definition or define))	USPAT;	2003/03/14 16:38
		and resin	US-PGPUB	
-	1	("6350664").PN.	USPAT;	2003/03/14 17:21
I		1	US-PGPUB	2002/02/14 17 10
-	7	("4043027"   "6130116"   "6184064"   ,"6190946"   "6197616"   "6204091"	USPAT	2003/03/14 17:10
İ	1	"6221751").PN.	1	
_	1	("6262513").PN.	USPAT;	2003/03/14 17:50
1	1		US-PGPUB	
ļ. <del>-</del>	4	("4364017"   "4734608"   "5010270"	USPAT	2003/03/14 17:22
ļ _	1	"5243250").PN. ("4,602,31").PN.	USPAT;	2003/03/14 17:50
	;	1	US-PGPUB	
l -	1	("4,602,318").PN.	USPAT;	2003/03/14 17:50
i			US-PGPUB	2003/03/17 15:56
-	75	(curing near2 agent) with capsule	USPAT; US-PGPUB	2003/03/11 13:30
! _	. 19	((curing near2 agent) with capsule	USPAT;	2003/03/17 16:03
,	1	,) with (epoxy)	US-PGPUB	
! -	66	epoxy with ("anti foam" or "anti foaming")	USPAT;	2003/03/17 16:15
	1 000	/ /avnal or avnalling) with air with /ahaat	US-PGPUB USPAT;	2003/03/17 16:20
-	239	(expel or expelling) with air with (sheet or film)	US-PGPUB	2003/03/17 10.20
_	25	((expel or expelling) with air with (sheet	USPAT;	2003/03/17 16:19
	,	or film)) and (epoxy with resin)	US-PGPUB	1 - 1 1 1 - 1 - 1 - 1 - 1 - 1 -
1 — 1	35		USPAT;	2003/03/17 16:19
i	. 10	or film)) and (epoxy) (((expel or expelling) with air with	US-PGPUB USPAT;	2003/03/17 16:19
; <del>"</del>	, 10	(sheet or film)) and (epoxy)) not ((expel	US-PGPUB	1000,00,1. 10.15
i	4	or expelling) with air with (sheet or		
i		film)) and (epoxy with resin))		1 0000 400 417 55 55
! _	733	(expel\$4) with air with (sheet or film or	USPAT;	2003/03/17 16:58
_	50	layer or encapsulant or encapsulation) ((expel\$4) with air with (sheet or film or	US-PGPUB USPAT;	2003/03/17 16:23
"	, 50	, layer or encapsulant or encapsulation))	US-PGPUB	,,,
I	1	and (IC or (packaging and (IC or		1
1	•	semiconductor or chip)) or chip)		0000/00/15 16 0:
<del>-</del>	. 4	· ("5074036"   "5720100"   "5843251"	USPAT	2003/03/17 16:24
i	0	"6077382").PN. 6312551.URPN.	USPAT	2003/03/17 16:25
; <del>-</del>		· ("5767575"   "5920126").PN.	USPAT	2003/03/17 16:26
	•			

	0 ) 6160000 uppy	HODAM	T 2003/03/17 16:26
_	2 6153939. URPN.	USPAT	2003/03/17 16:27
-	10 ("2308453"   "2697253"   "5049055"	USPAT	2003/03/1/ 16:2/
1	"5099090"   "5123823"   "5385869"		
1	"5522713"   "5609889"   "5766535"		
1	, "5766972").PN.		1 0000 (00 (17 16 00
1	0   5554413.URPN.	USPAT	2003/03/17 16:29
!	8 ("3597816"   "5009744"   "5046236"	USPAT	2003/03/17 16:30
	"5153859"   "5217550"   "5261986"		
	"5316602"   "5356512").PN.		
i _	6 ("4452659"   "4539063"   "4859269"	USPAT	2003/03/17 16:31
1	"4902371"   "5047110"   "5073223").PN.	1	
i <b>-</b>	2 5217550.URPN.	USPAT	2003/03/17 16:32
-	3 ("4799984"   "4929295"   "5009744").PN.	USPAT	2003/03/17 16:33
! -	1561 ((eliminat\$3 or reducing or reduce or	USPAT;	2003/03/17 16:40
1	preventing) with air with (sheet or film	US-PGPUB	
i	or layer)) and (IC or (packaging and (IC		
	or semiconductor or chip)) or chip or		
1	semiconductor)		-
l _	254 (((eliminat\$3 or reducing or reduce or	USPAT;	2003/03/17 16:42
	preventing) with air with (sheet or film	US-PGPUB	1
	or layer)) and (IC or (packaging and (IC		
ļ	or semiconductor or chip)) or chip or		
1	semiconductor)) and (epoxy with resin)	:	
. –	4 ("5420452"   "6020590"   "6242746"	USPAT	2003/03/17 16:51
	"6262408").PN.		
	0 6392217.URPN.	USPAT	2003/03/17 16:52
1_	351 (expel\$4) with air ) and ((lamination or	USPAT;	2003/03/17 17:00
	laminating or laminated) same (sheet or	US-PGPUB	
1	"epoxy resin")	1 - 2 - 2 - 2 - 2 - 2	I
: -	74 ((expel\$4) with air ) and ((lamination or	USPAT;	2003/03/17 17:00
	laminating or laminated) same (sheet or	US-PGPUB	
	"epoxy resin")) and (IC or (packaging and	10000	
1	(IC or semiconductor or chip)) or chip or	1	1
	semiconductor)	-	•
	Senitconductor)		



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